

www.nanoshel.com

Gold Tin

Alloy Powder

NS6130-12-001327

Quick Facts

FORMULA	Au:Sn
FORM	Powder
CAS	7440-57-5



* This image is for graphic purposes only and does not represent the actual product.

TECHNICAL SPECIFICATIONS

99.9 %
Purity

10-25 μ m
Particle size - APS

Au:Sn
Formula

An alloy is a mixture of elements containing at least one metal. It retains metallic properties such as conductivity, ductility, opacity, and luster, while offering improved characteristics such as higher strength or hardness. Gold Tin Alloy is widely used as a solder and bonding material in hybrid, photonic, microelectronic, and optoelectronic device packaging. Gold-tin eutectic alloys are especially suitable for bonding electronic and optical components to ceramic carriers. Alloys are broadly used across aerospace, military, industrial, medical, automotive, and manufacturing applications

Applications



• Microelectronic Packaging

• Optoelectronic Devices

• Semiconductor Die Bonding

• Hermetic Sealing

• Aerospace & Defense Electronics

PACK SIZES

25 g / 50 g / 100 g / 500 g / Bulk orders



ISO 9001:2015
CERTIFIED COMPANY

www.nanoshel.com
sales@nanoshel.com



INDIA
Intelligent Materials Pvt Ltd
Derabassi
Punjab (140507)
INDIA
+91 9779 550077, 9779238252

UNITED KINGDOM
Nanoshel UK Limited
Chapel House,
Chapel St Cheshire,
CW12 4AB United Kingdom
+44 (0) 74 105 488, +44 203 137 5187

UNITED STATES
Nanoshel LLC
3422 Old Capitol Suit
1305 Wilmington DE - 19808
United States
+1 646 470 4911

